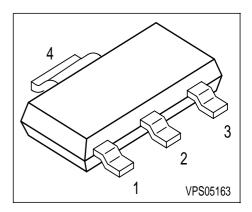


PNP Silicon AF Power Transistors

- For AF driver and output stages
- High current gain
- Low collector-emitter saturation voltage
- Complementary types: BDP951...BDP955 (NPN)



Туре	Marking	Pin Configuration				Package
BDP952	BDP 952	1 = B	2 = C	3 = E	4 = C	SOT223
BDP954	BDP 954	1 = B	2 = C	3 = E	4 = C	SOT223
BDP956	BDP 956	1 = B	2 = C	3 = E	4 = C	SOT223

Maximum Ratings

Parameter	Symbol	BDP952	BDP954	BDP956	Unit
Collector-emitter voltage	V _{CEO}	80	100	120	V
Collector-base voltage	V_{CBO}	100	120	140	
Emitter-base voltage	V _{EBO}	5	5	5	
DC collector current	I _C	3			Α
Peak collector current	I _{CM}	5			
Base current	I_{B}	200			mA
Peak base current	I _{BM}	500			
Total power dissipation, $T_S = 99 ^{\circ}\text{C}$	P _{tot}	3			W
Junction temperature	T_{i}	150			°C
Storage temperature	$T_{\rm stg}$	-65 150			
Thermal Resistance					
Junction - soldering point ¹⁾	R _{thJS}		≤17		K/W

1

 $^{^{1}}$ For calculation of R_{thJA} please refer to Application Note Thermal Resistance



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified.

Parameter		Symbol	Values			Unit
			min.	typ.	max.	
DC Characteristics		•				•
Collector-emitter breakdown voltage		V _{(BR)CEO}				V
$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0$	BDP952		80	-	-	
	BDP954		100	-	-	
	BDP956		120	-	-	
Collector-base breakdown voltage		V _{(BR)CBO}				
$I_{\rm C} = 100 \ \mu \text{A}, \ I_{\rm B} = 0$	BDP952		100	-	-	
	BDP954		120	-	-	
	BDP956		140	-	-	
Emitter-base breakdown voltage		V _{(BR)EBO}	5	-	-	
$I_{\rm E} = 10 \mu \text{A}, I_{\rm C} = 0$		(21.7,255)				
Collector cutoff current		I _{CBO}	-	-	100	nA
$V_{\rm CB} = 100 \text{ V}, I_{\rm E} = 0$						
Collector cutoff current		I _{CBO}	-	-	20	μΑ
$V_{\text{CB}} = 100 \text{ V}, I_{\text{E}} = 0, T_{\text{A}} = 150 \text{ °C}$						
Emitter cutoff current		/ _{EBO}	-	-	100	nA
$V_{EB} = 4 \text{ V}, I_{C} = 0$						
DC current gain 1)		h _{FE}				-
$I_{\rm C} = 10 \text{ mA}, \ V_{\rm CE} = 5 \text{ V}$			25	-	-	
$I_{\rm C} = 500 \text{ mA}, \ V_{\rm CE} = 1 \text{ V}$			40	-	475	
$I_{\rm C} = 2 \text{ A}, \ V_{\rm CE} = 2 \text{ V}$			15	-	-	
Collector-emitter saturation voltage1)		V _{CEsat}	-	-	0.8	٧
$I_{\rm C} = 2 \text{A}, \ I_{\rm B} = 0.2 \text{A}$						
Base-emitter saturation voltage 1)		V _{BEsat}	-	-	1.5	
$I_{\rm C} = 2 \text{A}, I_{\rm B} = 0.2 \text{A}$						
AC Characteristics						•
Transition frequency		f _T	-	100	-	MHz
$I_{\rm C} = 50 \text{ mA}, \ V_{\rm CE} = 10 \text{ V}, \ f = 100 \text{ M}$	Hz	'				
Collector-base capacitance		C _{cb}	-	40	-	pF
$V_{\rm CB} = 10 \text{ V}, f = 1 \text{ MHz}$						

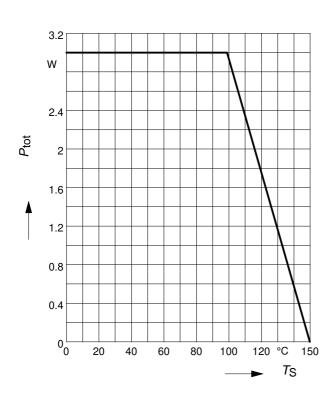
2

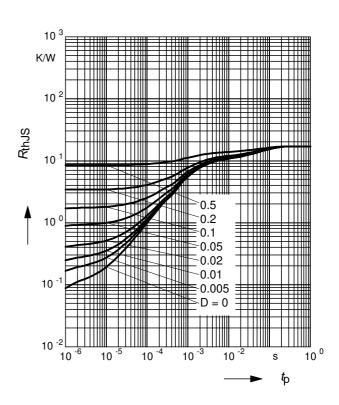
¹⁾ Pulse test: $t \le 300\mu s$, D = 2%



Total power dissipation $P_{tot} = f(T_S)$

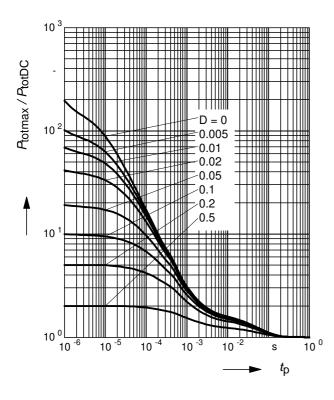
Permissible Pulse Load $R_{thJS} = f(t_p)$





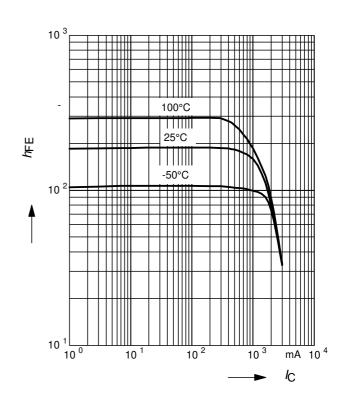
Permissible Pulse Load

$$P_{\text{totmax}} / P_{\text{totDC}} = f(t_p)$$



DC current gain $h_{FE} = f(I_C)$

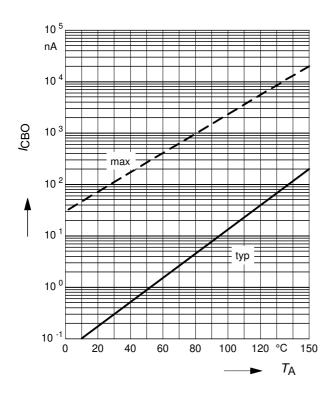
$$V_{CE} = 2V$$





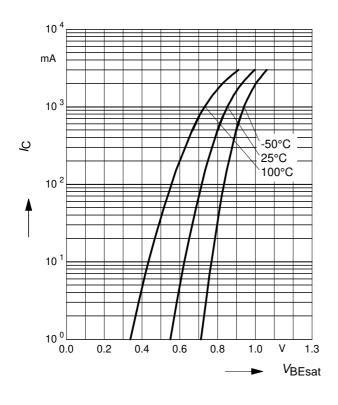
Collector cutoff current $I_{CBO} = f(T_A)$

$$V_{\rm CB} = 45 \text{V}$$



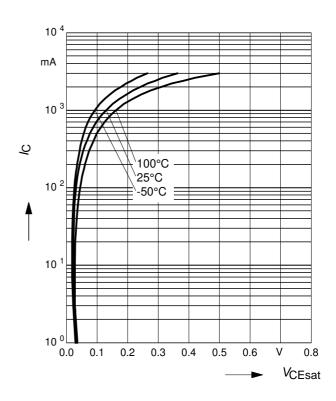
Base-emitter saturation voltage

$$I_{\text{C}} = f(V_{\text{BEsat}}), h_{\text{FE}} = 10$$



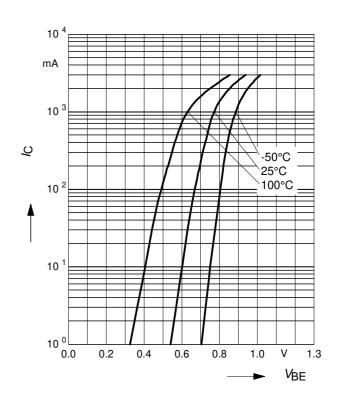
Collector-emitter saturation voltage

$$I_{\rm C} = f(V_{\rm CEsat}), h_{\rm FE} = 10$$



Collector current $I_{C} = f(V_{BE})$

$$V_{CE} = 2V$$



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